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(31) Priority Document No	:NA	(72)Name of Inventor :
(32) Priority Date	:NA	1)Dr.T.Somanathan
(33) Name of priority country	:NA	2)Dr. Dinesh T
(86) International Application No	:	3)Dr. M. Parthasarathy
Filing Date	:01/01/1900	4)Dr. D. Karunakaran
(87) International Publication No	: NA	5)Dr. K. M. Kumar
(61) Patent of Addition to Application Number	:NA	6)Dr.K.Karunakaran
Filing Date	:NA	7)Dr.S.Sivabalan
(62) Divisional to Application Number	:NA	8)Mr. Omkar A. Jarali
Filing Date	:NA	9)Dr. V. Gowthami
		10)Dr.A.Parthiban
		11)Er. Lokesh Pattnaik

(57) Abstract :

ABSTRACT COPPER NANO COATED RADIATOR FOR ENHANCED THERMAL EFFICIENCY The present invention discloses a copper nano coated radiator for enhanced thermal efficiency. The copper nano coated radiator comprises a radiator body comprising a plurality of heat exchange tubes and fins configured to transfer heat from a working fluid to an окружа surrounding medium. The base substrate forming the heat exchange tubes and fins. The copper nano-coating layer uniformly deposited on at least an outer surface of the heat exchange tubes and fins, wherein the copper nano-coating layer comprises copper nanoparticles having a nano-scale dimension and is configured to increase surface area, thermal conductivity, and heat transfer efficiency of the radiator as compared to an uncoated radiator. The copper nanoparticles have an average particle size in the range of 1 nm to 100 nm. The copper nano-coating layer is deposited by at least one of electrochemical deposition, physical vapor deposition, chemical vapor deposition, thermal spraying, or sol-gel coating. The copper nano-coating layer has a thickness in the range of 50 nm to 10 micrometers.

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